

SUA-110E5-30xx-S277

鍍層厚度 :	HOUSING :
Blank : 1u"	Blank : LCP,Blue
2 : 15u"	K : LCP,Black
3 : 30u"	GR : PBT,Green

NOTE:

1.MATERIAL:

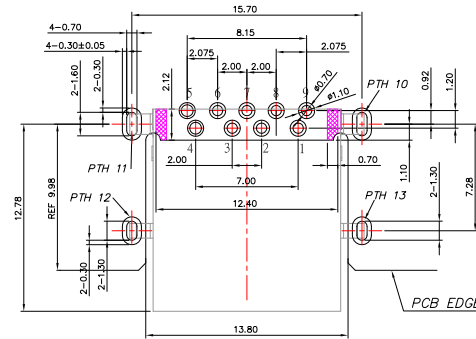
- 1.1 Housing: Plastic,(UL94V-0)
- 1.2 Contact: Phosphor Bronze
- 1.3 Shell: SUS

2.Finish:

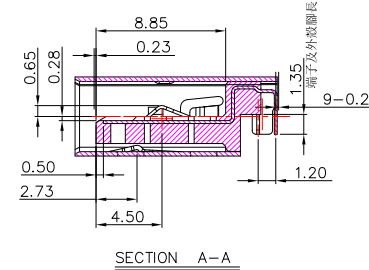
- 2.1 Contact: Plated Gold in Mating Area ;
Tin Plated on Solder Balls ;
Nickel under plated overall
- 2.2 Shell: Nickel under Plated surface layer

3.SPECIFICATION:

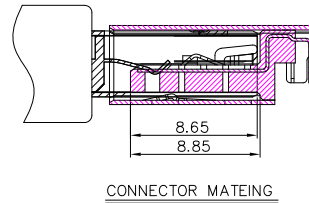
- 3.1 Rate: 30V DC , 1.5 A
- 3.2 insulator Resistance:100MΩ Min
- 3.3 Dielectric Strength: 500V AC
- 3.4 Contact Resistance: 30mΩ Max
- 3.5 Operation Temperature: -55°C ~ +85°C
- 3.6 Insertion Force: 35 N
- 3.7 Extraction Force: 10 N



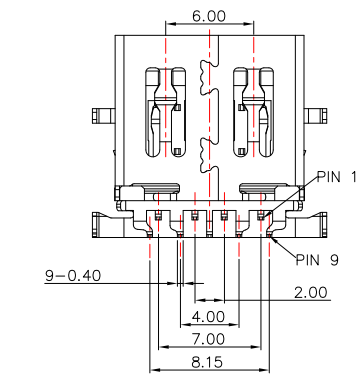
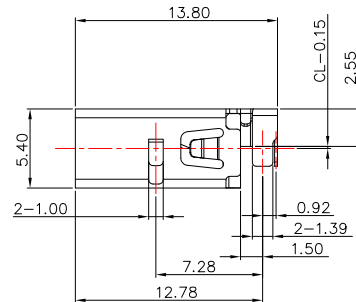
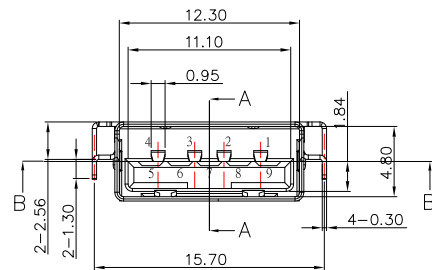
RECOMMENDED PCB LAYOUT



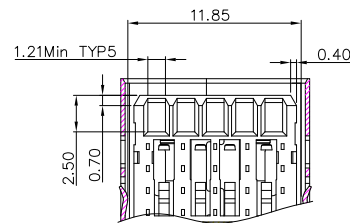
SECTION A-A



CONNECTOR MATEING



(BOTTOM VIEW)



SECTION B-B

Pin #	SIGNAL NAME	DESCRIPTION	MATING SEQUENCE
1	VBUS	POWER	SECOND
2	D-	USB 2.0 DIFFERENTIAL PAIR	THIRD
3	D+		
4	GND	GROUND FOR POWER RETURN	SECOND
5	Std_A_SSRX-	SUPERSPEED RECEIVER DIFFERENTIAL PAIR	LAST
6	Std_A_SSRX+		
7	GND_DRAIN	GROUND FOR SIGNAL RETURN	
8	Std_A_SSTX-	SUPERSPEED TRANSMITTER DIFFERENTIAL PAIR	
9	Std_A_SSTX+		
Shell	Shield	CONNECTOR METAL SHELL	FRIST

ITEM NO.	DESCRIPTION	DRAWN	DATE
3	新增PCB LAYOUT尺寸標註	Lan	041819
2	新增顏色及材質選項	Jack	042817
1	更新PCB LAYOUT尺寸	Jack	012017

CONTACT 建倚科技股份有限公司
CONTACT TECHNOLOGY CORP.

TOLERANCE UNLESS OTHERWISE STATED :
 Up to 5 ±0.2
 Above 5 ~ 15 ±0.3
 Above 15 ~ 30 ±0.4
 Above 30 ~ 50 ±0.5
 Angle ±0.3

3RD. ANGEL'S



UNITS MM

DRAWN BY:	DATE	MAT'L	TITLE	CONNECTOR
Jack Lu	04/18/19	FINISH	MODLE	USB A/F 3.0 DIP 沉板, 板上H:2.56mm, 無捲邊反向
CHECKED BY:	DATE	SCALE	DWG NO.	SUA-110E5-30xx-S277
Jacky Chen	04/18/19	1 : 1	PART NO.	SUA-110E5-30xx-S277
APPROVED BY:	DATE	SHEET NO.	1 of 1	
Tony Kao	04/18/19			

SIZE A4
VER R3